



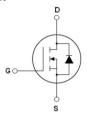
N-Channel Super Junction Power MOSFET III

General Description

The series of devices use advanced super junction technology and design to provide excellent R_{DS(ON)} with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

Features

- ◆ New technology for high voltage device
- ◆ Low on-resistance and low conduction losses
- ◆ Small package
- ◆ Ultra Low Gate Charge cause lower driving requirements
- ◆ 100% Avalanche Tested
- ◆ ROHS compliant





Schematic diagram

TO-220F

Application

- ◆ Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- ◆ Uninterruptible Power Supply (UPS)

VDS	800	V
Rds(on)max	900	mΩ
ID	6	А

Package Marking And Ordering Information

Device	Device Package	Marking	
MJ80T900F	TO-220F	MJ80T900F	

Table 1. Absolute Maximum Ratings (Tc=25℃)

Parameter	Symbol	MJ80T900F	Unit	
Drain-Source Voltage (Ves=0V)	VDS	800	V	
Gate-Source Voltage (V _{DS} =0V) ,AC (f>1 Hz)	Vgs	±30	V	
Continuous Drain Current at Tc=25°C	ID (DC)	6*	Α	
Continuous Drain Current at Tc=100°C	ID (DC)	3.8*	А	
Pulsed drain current (Note 1)	IDM (pluse)	24*	А	
Maximum Power Dissipation (Tc=25℃)	Po	32.4	VV	
Derate above 25°C	Po	0.26	W/°C	
Single pulse avalanche energy (Note 2)	Eas	100	mJ	
Avalanche current (Note 1)	lar	5	А	
Repetitive Avalanche energy, tar limited by T _{jmax} (Note 1)	Ear	0.3	mJ	

Parameter	Symbol	MJ80T900F	Unit
Drain Source voltage slope, V _{DS} ≤480 V	dv/dt	50	V/ns
Reverse diode dv/dt, V _{DS} ≤480 V,I _{SD} <i<sub>D</i<sub>	dv/dt	15	V/ns
Operating Junction and Storage Temperature Range	TJ,Tsтg	-55+150	°C





Table 2. Thermal Characteristic

Parameter	Symbol	MJ80T900F	Unit
Thermal Resistance, Junction-to-Case (Maximum)	RthJC	3.86	°C/W
Thermal Resistance, Junction-to-Ambient (Maximum)	RthJA	80	°C/W

Table 3. Electrical Characteristics (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V I _D =250µA	800	-	-	V
Zero Gate Voltage Drain Current (Tc=25°C)	loss	V _{DS} =800V,V _{GS} =0V	-	_	1	μΑ
Zero Gate Voltage Drain Current (Tc=125°C)	loss	V _{DS} =800V,V _{GS} =0V	-	-	100	μΑ
Gate-Body Leakage Current	lgss	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	3	3.5	4	V
Drain-Source On-State Resistance	Rds(on)	V _{GS} =10V,I _D =4A	-	750	900	mΩ
Dynamic Characteristics						
Forward Transconductance	grs	V _{DS} =20V,I _D =4A	-	6	-	S
Input Capacitance	Cies		-	1320	-	pF
Output Capacitance	Coss VDS=50V,VGS=0V F=1.0MHz		-	33	-	pF
Reverse Transfer Capacitance	Crss	-	-	2	-	pF
Total Gate Charge	Qg	Qg -		22.8	-	nC
Gate-Source Charge	Q _{gs} V _{DS} =640V,I _D =6A - 7.7		7.7	-	nC	
Gate-Drain Charge	Qgd			6.9	-	nC
Switching times						
Turn-on Delay Time	t _{d(on)}	V _{DD} =400V,I _D =3A	-	10	-	nS
Turn-on Rise Time	tr		-	5	-	nS
Turn-Off Delay Time	t _{d(off)}	R _G =3Ω,V _{GS} =10V	-	53	70	nS
Turn-Off Fall Time	tf	-	-	6	9	nS
Source- Drain Diode Characteristics	l					ı
Source-drain current (Body Diode)	Isp		-	-	6	А
Pulsed Source-drain current (Body Diode)	Tc=25°C		-	-	24	А
Forward On Voltage	Vsp	Vsb Tj=25°C,lsb=6A,Ves=0V		0.9	1.2	V
Reverse Recovery Time	trr		-	260	-	nS
Reverse Recovery Charge	Qrr	T _j =25°C,l⊧=3A di/dt=100A/µs	-	1.7	-	uC
Peak reverse recovery Current	Irrm	·			_	Α

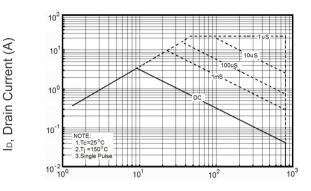




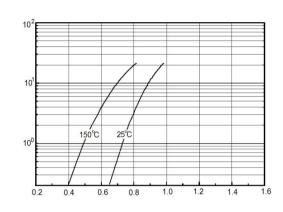
Notes

- 1.Repetitive Rating: Pulse width limited by maximum junction temperature
- $2.T_j=25^{\circ}C,V_{DD}=50V,V_{G}=10V,R_{G}=25\Omega$

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

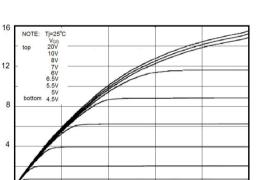


DR, Reverse Drain Current(A)



V_{DS}, Drain-Source Voltage (V)

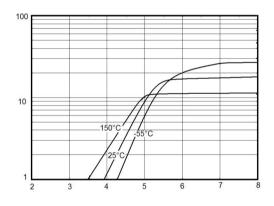
Figure 1 Safe operating area



I_D, Drain Current (A)

Vsp,Source-Drain Voltage(V)

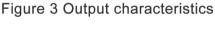
Figure 2 Source-Drain Diode Forward Voltage



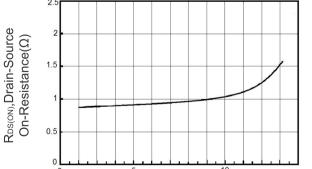
V_{GS}, Gate-Source Voltage (V)

Figure 4 Transfer characteristics

V_{DS}(V)



10



 $\mathsf{R}_{\mathsf{DS}(\mathsf{ON})}$, Drain-Source On-Resistance(Ω)

2.5 2.5 1.5 0.60 -20 20 60 100 140 180

ID, Drain Current (A)

Figure 5 Static drain-source on resistance

TJ, Junction Temperature (°C)
Figure 6 RDS(ON) vs Junction
Temperature



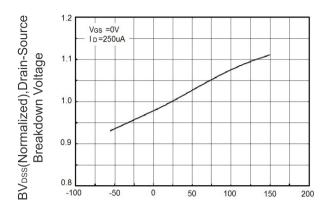
Ves, Gate-Source Voltage (V)

6

4

2

0



l₀, Drain Current (A)

Capacitances(pF)

10 8 6 4 2 0 25 50 75 100 125 150

T_J, Junction Temperature (°C)

Figure 7 BVDSS vs Junction Temperature

16

20

24

Tc, Case Temperature (°C)
Figure 8 Maximum Ib vs Junction
Temperature

Q_G,Total Gate Charge(nC)

Figure 9 Gate charge waveforms

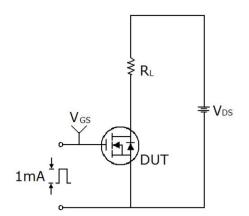
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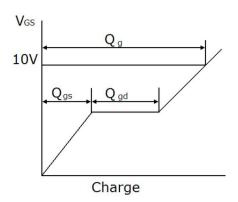
t₅,Square Wave Pulse(S)

Figure 11 Transient Thermal Impedance

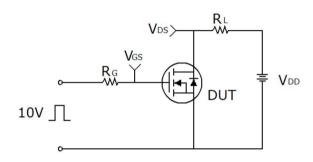
V_{DS}, Drain-Source Voltage (V) Figure 10 Capacitance

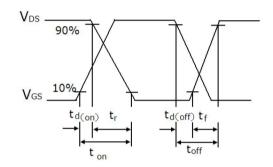
Test circuit



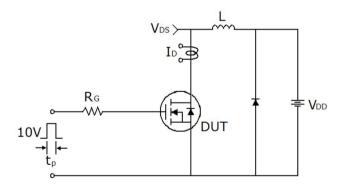


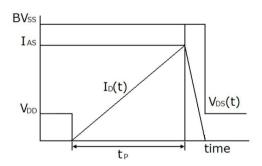
Gate charge test circuit & Waveform





Switch Time Test Circuit



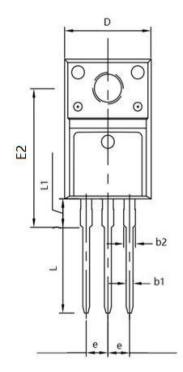


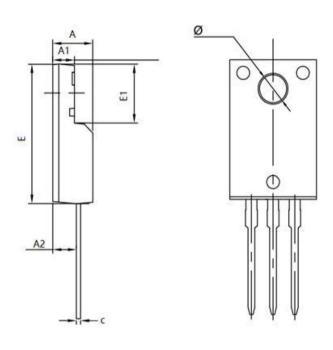
Unclamped Inductive Switching Test Circuit & Waveforms





TO-220F Package Information





Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
А	4.500	4.900	0.177	0.193
A1	2.340	2.740	0.092	0.108
A2	2.560	2.960	0.101	0.117
b1	0.700	0.900	0.028	0.035
b2	1.180	1.580	0.046	0.062
С	0.400	0.600	0.016	0.024
D	9.960	10.360	0.392	0.408
E	15.670	15.970	0.617	0.629
E1	6.500	6.900	0.256	0.272
E2	15.500	16.100	0.610	0.634
е	2.540	2.540 TYP		TYP
Φ	3.080	3.280	0.121	0.129
L	12.640	13.240	0.498	0.521
L1	3.030	3.430	0.119	0.135





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